

STN	Skúšobné metódy na elektrotechnické materiály, dosky s plošnými spojmi a iné spájacie štruktúry a zostavy. Časť 2-719: Skúšobné metódy na materiály na spájacie štruktúry. Relatívna permitivita a stratový činiteľ (500 MHz až 10 GHz).	STN EN 61189-2-719
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Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2-719: Test methods for materials for interconnection structures - Relative permittivity and loss tangent (500 MHz to 10 GHz)

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 03/17

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English Version

Test methods for electrical materials, printed boards and other
interconnection structures and assemblies -
Part 2-719: Test methods for materials for interconnection
structures - Relative permittivity and loss tangent (500 MHz to 10
GHz)
(IEC 61189-2-719:2016)

Méthode d'essai pour les matériaux électriques, les cartes
imprimées et autres structures d'interconnexion et
ensembles - Partie 2-719: Méthodes d'essai des matériaux
pour structures d'interconnexion - Permittivité relative et
tangente de perte (500 MHz à 10 GHz)
(IEC 61189-2-719:2016)

Prüfverfahren für Elektromaterialien, Leiterplatten und
andere Verbindungsstrukturen und Baugruppen -
Teil 2-719: Prüfverfahren für Materialien von
Verbindungsstrukturen - Relative Permittivität und
Verlustfaktor (500 MHz bis 10 GHz)
(IEC 61189-2-719:2016)

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Europäisches Komitee für Elektrotechnische Normung

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EN 61189-2-719:2016**European foreword**

The text of document 91/1366/FDIS, future edition 1 of IEC 61189-2-719, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 61189-2-719:2016.

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<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194	-	Printed board design, manufacture and assembly - Terms and definitions	-	-



INTERNATIONAL STANDARD

NORME INTERNATIONALE



Test methods for electrical materials, printed boards and other interconnection structures and assemblies –

Part 2-719: Test methods for materials for interconnection structures – Relative permittivity and loss tangent (500 MHz to 10 GHz)

Méthode d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles –

Partie 2-719: Méthodes d'essai des matériaux pour structures d'interconnexion – Permittivité relative et tangente de perte (500 MHz à 10 GHz)





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INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Test methods for electrical materials, printed boards and other interconnection structures and assemblies –
Part 2-719: Test methods for materials for interconnection structures – Relative permittivity and loss tangent (500 MHz to 10 GHz)**

**Méthode d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles –
Partie 2-719: Méthodes d'essai des matériaux pour structures d'interconnexion – Permittivité relative et tangente de perte (500 MHz à 10 GHz)**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS AND
OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –****Part 2-719: Test methods for materials for interconnection structures –
Relative permittivity and loss tangent (500 MHz to 10 GHz)**

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International Standard IEC 61189-2-719 has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/1366/FDIS	91/1380/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

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TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 2-719: Test methods for materials for interconnection structures – Relative permittivity and loss tangent (500 MHz to 10 GHz)

1 Scope

This part of IEC 61189 specifies a test method of relative permittivity and loss tangent of printed board and assembly materials, expected to be determined 2 to 10 of relative permittivity and 0,001 to 0,050 of loss tangent at 500 MHz to 10 GHz.

2 Normative references

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